

Pang Jhl Or Pang Hlj

List of Publications by Year
in descending order

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94
papers

2,446
citations

279798
23
h-index

302126
39
g-index

102
all docs

102
docs citations

102
times ranked

1277
citing authors

#	ARTICLE	IF	CITATIONS
1	An integrated fatigue assessment approach of rail welds using dynamic 3D FE simulation and strain monitoring technique. Engineering Failure Analysis, 2021, 120, 105080.	4.0	4
2	Investigation on material characteristics and fatigue crack behavior of thermite welded rail joint. Construction and Building Materials, 2021, 276, 122249.	7.2	22
3	Structural fatigue investigation of thermite welded rail joints considering weld-induced residual stress and stress relaxation by cyclic load. Engineering Structures, 2021, 235, 112033.	5.3	14
4	Directed energy deposition build process control effects on microstructure and tensile failure behaviour. Journal of Materials Processing Technology, 2021, 294, 117139.	6.3	11
5	Dynamic finite element modeling and fatigue damage analysis of thermite welds. Fatigue and Fracture of Engineering Materials and Structures, 2020, 43, 119-136.	3.4	2
6	Structural fatigue investigation of transverse surface crack growth in rail steels and thermite welds subjected to in-plane and out-of-plane loading. Engineering Structures, 2020, 204, 110076.	5.3	17
7	Finite element and experimental study on multiaxial fatigue analysis of rail clip failures. Fatigue and Fracture of Engineering Materials and Structures, 2020, 43, 2390-2401.	3.4	14
8	A YOLOv3-based Deep Learning Application Research for Condition Monitoring of Rail Thermite Welded Joints. , 2020, , .		8
9	Characterisation of porosity, density, and microstructure of directed energy deposited stainless steel AISI 316L. Additive Manufacturing, 2019, 25, 286-296.	3.0	41
10	Metro Door System Reliability, Availability and Maintainability Analysis. , 2018, , .		1
11	Mechanical Properties and Microstructural Analysis of Rail Thermite Welding Joints. , 2018, , .		2
12	Microstructure and Wear Performance Assessment of Laser Cladded Rail Steel for Service Life Extension at Sharp-Radius Curves. , 2018, , .		0
13	Failure Assessment Diagram (FAD) analysis of fatigue test results for X65 welded joints. MATEC Web of Conferences, 2018, 165, 21011.	0.2	1
14	Effects of laser cladding on fatigue performance of AISI 4340 steel in the as-clad and machine treated conditions. Journal of Materials Processing Technology, 2017, 243, 246-257.	6.3	39
15	Fatigue life prediction model for laser clad AISI 4340 specimens with multiple surface cracks. International Journal of Fatigue, 2016, 87, 235-244.	5.7	22
16	Stress intensity factors for fatigue analysis of weld toe cracks in a girth-welded pipe. International Journal of Fatigue, 2016, 87, 279-287.	5.7	26
17	Damage monitoring using fiber optic sensors and by analysing electro-mechanical admittance signatures obtained from piezo sensor. Proceedings of SPIE, 2015, , .	0.8	1
18	Thermo-mechanical model for simulating laser cladding induced residual stresses with single and multiple clad beads. Journal of Materials Processing Technology, 2015, 224, 89-101.	6.3	120

#	ARTICLE	IF	CITATIONS
19	A general methodology for calculating mixed mode stress intensity factors and fracture toughness of solder joints with interfacial cracks. Engineering Fracture Mechanics, 2014, 131, 9-25.	4.3	15
20	Fatigue Growth Analysis of Pre Induced Surface Defects Using Piezoelectric Wafer Based Impedance Method and Digital Image Correlation System. Journal of Nondestructive Evaluation, 2014, 33, 413-426.	2.4	11
21	Electrochemical capacitive properties of CNT fibers spun from vertically aligned CNT arrays. Journal of Solid State Electrochemistry, 2012, 16, 1775-1780.	2.5	52
22	Fracture of Sn-Ag-Cu Solder Joints on Cu Substrates: I. Effects of Loading and Processing Conditions. Journal of Electronic Materials, 2012, 41, 375-389.	2.2	32
23	Impact of Thermal Cycling on Sn-Ag-Cu Solder Joints and Board-Level Drop Reliability. Journal of Electronic Materials, 2008, 37, 880-886.	2.2	88
24	Effect of Stress State on Growth of Interfacial Intermetallic Compounds Between Sn-Ag-Cu Solder and Cu Substrates Coated with Electroless Ni Immersion Au. Journal of Electronic Materials, 2008, 37, 1843-1850.	2.2	18
25	Digital image correlation for solder joint fatigue reliability in microelectronics packages. Microelectronics Reliability, 2008, 48, 310-318.	1.7	20
26	The influence of solder volume and pad area on Sn-3.8Ag-0.7Cu and Ni UBM reaction in reflow soldering and isothermal aging. Microelectronics Reliability, 2008, 48, 611-621.	1.7	30
27	Thermal cycling fatigue analysis of copper pillar-to-solder joint reliability. , 2008, , .		5
28	Strain-rate effects on mechanical properties for SAC387 and SAC105-Y solder. , 2008, , .		2
29	Flip chip solder joint reliability analysis using viscoplastic and elastic-plastic-creep constitutive models. IEEE Transactions on Components and Packaging Technologies, 2006, 29, 355-363.	1.3	48
30	Drop impact reliability testing for lead-free and lead-based soldered IC packages. Microelectronics Reliability, 2006, 46, 1160-1171.	1.7	144
31	Determination of interface fracture toughness of adhesive joint subjected to mixed-mode loading using finite element method. International Journal of Adhesion and Adhesives, 2006, 26, 249-260.	2.9	30
32	in-situ electromigration study on Sn~Ag~Cu solder joint by digital image speckle analysis. Journal of Electronic Materials, 2006, 35, 1993-1999.	2.2	2
33	Nanoindentation on SnAgCu lead-free solder joints and analysis. Journal of Electronic Materials, 2006, 35, 2107-2115.	2.2	46
34	Electromigration effect on intermetallic growth and Young's modulus in SAC solder joint. Journal of Electronic Materials, 2006, 35, 2116-2125.	2.2	25
35	Nanoindentation on SnAgCu lead-free solder and analysis. , 2005, , .		1
36	Foreword Special Section on ITherm 2004 Mechanics Track. IEEE Transactions on Components and Packaging Technologies, 2005, 28, 387-389.	1.3	0

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37	Isothermal and thermal cycling aging on IMC growth rate in lead-free and lead-based solder interface. IEEE Transactions on Components and Packaging Technologies, 2005, 28, 408-414.	1.3	77
38	Mechanical Properties for 95.5Sn-3.8Ag-0.7Cu Lead-Free Solder Alloy. IEEE Transactions on Components and Packaging Technologies, 2005, 28, 830-840.	1.3	72
39	Intermetallic growth studies on Sn-Ag-Cu lead-free solder joints. Journal of Electronic Materials, 2004, 33, 1219-1226.	2.2	101
40	Thermal cycling aging effects on Sn-Ag-Cu solder joint microstructure, IMC and strength. Thin Solid Films, 2004, 462-463, 370-375.	1.8	180
41	Reliability of PBGA assemblies under out-of-plane vibration excitations. IEEE Transactions on Components and Packaging Technologies, 2002, 25, 293-300.	1.3	35
42	Thermal cycling analysis of flip-chip solder joint reliability. IEEE Transactions on Components and Packaging Technologies, 2001, 24, 705-712.	1.3	142
43	Thermal cycling aging effects on microstructural and mechanical properties of a single PBGA solder joint specimen. IEEE Transactions on Components and Packaging Technologies, 2001, 24, 10-15.	1.3	35
44	Mechanical deflection system (MDS) test and methodology for PBGA solder joint reliability. IEEE Transactions on Advanced Packaging, 2001, 24, 507-514.	1.6	17
45	Flip chip on board solder joint reliability analysis using 2-D and 3-D FEA models. IEEE Transactions on Advanced Packaging, 2001, 24, 499-506.	1.6	72
46	Microstructure and intermetallic growth effects on shear and fatigue strength of solder joints subjected to thermal cycling aging. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2001, 307, 42-50.	5.6	140
47	Vibration reliability characterization of PBGA assemblies. Microelectronics Reliability, 2000, 40, 1097-1107.	1.7	52
48	Thermal analysis of a wirebond chip-on-board package. , 0, , .		1
49	Thermo-mechanical analysis of solder joint fatigue and creep in a flip chip on board package subjected to temperature cycling loading. , 0, , .		26
50	Flip chip solder joint fatigue life model investigation. , 0, , .		15
51	Modeling thermal cycling and thermal shock tests for FCOB. , 0, , .		2
52	On the moduli of viscoelastic materials. , 0, , .		4
53	In-situ reliability analysis of solder joint by digital image correlation. , 0, , .		0
54	Bulk solder and solder joint properties for lead free 95.5Sn-3.8Ag-0.7Cu solder alloy. , 0, , .		54

#	ARTICLE	IF	CITATIONS
55	Effect of processing parameters on the morphology of the interfacial intermetallics between Cu and SnPb solders. , 0, , .		2
56	Mechanical failure strength characterization of silicon dice. , 0, , .		10
57	Solder joint reliability modeling of 96.5Sn/3.5Ag flip chip bumps under temperature cycling condition. , 0, , .		5
58	Modeling plated copper interconnections in a bumpless flip chip package. , 0, , .		8
59	Design for reliability (DFR) methodology for electronic packaging assemblies. , 0, , .		32
60	Application of digital speckle correlation to micro-deformation measurement of a flip chip assembly. , 0, , .		7
61	Creep and fatigue characterization of lead free 95.5Sn-3.8Ag-0.7Cu solder. , 0, , .		61
62	Lead-free 95.5Sn-3.8Ag-0.7Cu solder joint reliability analysis for micro-BGA assembly. , 0, , .		15
63	In-situ electromigration studies on Sn-Ag-Cu solder joint by digital image speckle analysis (DISA). , 0, , .		0
64	Drop test reliability assessment of leaded & lead-free solder joints for IC packages. , 0, , .		15
65	Isothermal and thermal cycling aging on IMC growth rate in Pb-free and Pb-based solder interfaces. , 0, , .		8
66	Thermal fatigue reliability analysis for PBGA with Sn-3.8Ag-0.7Cu solder joints. , 0, , .		37
67	Vibration fatigue analysis for FCOB solder joints. , 0, , .		15
68	Modeling stress strain curves for lead-free 95.5Sn-3.8Ag-0.7Cu solder. , 0, , .		19
69	Mechanical characterization in failure strength of silicon dice. , 0, , .		32
70	Flip chip solder joint fatigue analysis using 2D and 3D FE models. , 0, , .		9
71	Lead-free 96.5Sn-3.5Ag flip chip solder joint reliability analysis. , 0, , .		9
72	Harsh solder joint reliability tests by impact drop and highly accelerated life test (HALT). , 0, , .		4

#	ARTICLE	IF	CITATIONS
73	Drop Reliability Performance Assessment for PCB Assemblies of Chip Scale Packages (CSP). , 0, , .		10
74	Lead free solder joint reliability characterization for PBGA, PQFP and TSSOP assemblies. , 0, , .		22
75	Drop Impact Reliability Testing for Lead-Free and Leaded Soldered IC Packages. , 0, , .		22
76	Intermetallic Growth and Failure Study for Sn-Ag-Cu/ENIG PBGA Solder Joints Subject to Thermal Cycling. , 0, , .		6
77	Digital Image Correlation and its Applications in Electronics Packaging. , 0, , .		5
78	Failure Study of Sn-Ag-Cu Lead-free Solder Joint by Digital Image Speckle Analysis (DISA). , 0, , .		1
79	Impact of Drop-In Lead Free Solders on Microelectronics Packaging. , 0, , .		4
80	Failure analysis of lead-free Sn-Ag-Cu solder joints for 316 I/O PBGA package. , 0, , .		0
81	Interfacial IMC and Kirkendall void on SAC Solder Joints subject to Thermal Cycling. , 0, , .		6
82	Investigation of IMC Layer Effect on PBGA Solder Joint Thermal Fatigue Reliability. , 0, , .		3
83	Isothermal cyclic bend fatigue test method for lead free solder joints. , 0, , .		7
84	Performance Assessment on Board-level Drop Reliability for Chip Scale Packages (Fine-Pitch BGA). , 0, , .		15
85	Drop Impact Analysis of Sn-Ag-Cu Solder Joints using Dynamic High-Strain Rate Plastic Strain as the Impact Damage Driving Force. , 0, , .		25
86	Thermal Deformation Measurement by Digital Image Correlation Method. , 0, , .		16
87	Intermetallic growth studies on SAC/ENIG and SAC/CU-OSP lead-free solder joints. , 0, , .		8
88	IMC consideration in FEA simulation for PB-free solder joint reliability. , 0, , .		6
89	In-Situ Study of the Effect of Electromigration on Strain Evolution and Mechanical Property Change in Lead-free Solder Joints. , 0, , .		3
90	Modeling Board-Level Four-Point Bend Fatigue and Impact Drop Tests. , 0, , .		11

#	ARTICLE	IF	CITATIONS
91	Combined Thermal and Electromigration Exposure Effect on SnAgCu BGA Solder Joint Reliability. , 0, , .		15
92	Effect of Intermetallic and Kirkendall Voids Growth on Board Level Drop Reliability for SnAgCu Lead-Free BGA Solder Joint. , 0, , .		27
93	Fatigue Crack Growth and Coalescence Algorithm Starting from Multiple Surface Cracks. Advanced Materials Research, 0, 891-892, 1003-1008.	0.3	2
94	Fatigue Monitoring of Double Surface Defects Using PZT Based Electromechanical Impedance and Digital Image Correlation Methods. Advanced Materials Research, 0, 891-892, 551-556.	0.3	5